ABSTRACT

FORMATION OF A WIRE BOND WITH ENHANCED PULL

A method of forming a wire connection using a bonding tool is provided. A first bond is first formed from a bonding wire fed from the bonding tool at a first bonding point. The bonding wire is then extended from the first bond while moving the bonding tool from the first bonding point towards a second bonding point. Thereafter, the bonding wire is mechanically deformed by contacting the bonding tool against a support surface and the bonding tool is moved in a direction away from the first bond to pull the bonding wire before forming a second bond with the bonding tool.

Figure 7